

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

A Printed-Circuit-Board (PCB) Module with a Milled-Back
Insulator Layer around Flat Metal Pads for Surface-Mounting to a
Larger Board

Application Number :

Confirmation Number:

First Named Applicant: Craig Taylor

Attorney Docket Number: PS-117

Art Unit:

Examiner:

Search string: (6759738 or 6759271 or 6637641 or 6609915 or 6566166 or 6245490 or 6137064
or 6134117 or 6104095 or 5670750 or 5074037),pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6759738	2004-07-06	Fallon , et al.	B1	257	700
	2	6759271	2004-07-06	Miyazaki	B1	257	E21.506
	3	6637641	2003-10-28	Downes , et al.	B1	228	102
	4	6609915	2003-08-26	Adams , et al.	B1	439	74
	5	6566166	2003-05-20	Chien	B1	438	108
	6	6245490	2001-06-12	Yoon , et al.	B1	430	318
	7	6137064	2000-10-24	Kiani , et al.	B1	174	266
	8	6134117	2000-10-17	Funk , et al.	B1	361	760
	9	6104095	2000-08-15	Shin , et al.	B1	257	787
	10	5670750	1997-09-23	Lauffer , et al.	B1	174	262
	11	5074037	1991-12-24	Sutcliffe , et al.	B1	29	847

Signature

Examiner Name	Date